What is claimed is:

1. A method for manufacturing an ~~An~~ integrated circuit package system comprising:

providing a substrate;

attaching a base die to the substrate, the base die having a relief region with a shaped cross-section; and

connecting a bond wire between an active base surface of the base die and the substrate, the bond wire extending through the shaped cross-section of the relief region.

2. The method~~system~~ as claimed in claim 1 wherein connecting the bond wire includes stitch bonding between the active base surface of the base die and the substrate, the bond wire extending through the shaped cross-section of the relief region.

3. The method~~system~~ as claimed in claim 1 wherein attaching the base die to the substrate, the base die having the relief region with the shaped cross-section, the relief region with the shaped cross-section is shaped as a rectangle, a triangle, or a curve.

4. The method~~system~~ as claimed in claim 1 further comprising:

mounting a stacking die over the base die; and

attaching a stacking attachment layer between the stacking die and the base die, the stacking attachment layer covering a portion of the bond wire.

5. The method ~~system~~ as claimed in claim 1 further comprising mounting a stacking die over the base die, the stacking die having a relief region with a shaped cross-section extending over the connection of the bond wire to the active base surface of the base die.

6. A method for manufacturing an ~~An~~ integrated circuit package system comprising:

providing a substrate having an active substrate surface;

attaching a base die to the substrate, the base die having a relief region with a shaped cross-section around the perimeter thereof; and

connecting a bond wire between an active base surface of the base die and the substrate, the bond wire ~~at least one of the bond wires~~ extending through the shaped cross-section of the relief region.

7. The method ~~system~~ as claimed in claim 6 further comprising a stitch bond connecting the bond wire parallel to the active base surface of the base die.

8. The method ~~system~~ as claimed in claim 6 further comprising:

mounting a stacking die over the base die; and

attaching an insulation layer on the stacking die, the insulation layer between the stacking die and the base die.

9. The method ~~system~~ as claimed in claim 6 further comprising:

mounting a stacking die over the base die, the stacking die having a relief region with a shaped cross-section;

attaching a stacking attachment layer between the stacking die and the base die, the stacking attachment layer covering a portion of the bond wire; and

wherein:

connecting the bond wire between the active base surface of the base die and the substrate, the bond wire ~~at least one of the bond wires~~ extending through the shaped-cross section of the relief region of the stacking die.

10. The method ~~system~~ as claimed in claim 6 further comprising mounting a stacking die over the base die, the stacking die having a relief region with a shaped cross-section extending over portions of the active base surface, the bond wire~~s~~, and portions of the substrate adjacent the bond wire~~s~~.

11. An integrated circuit package system comprising:

a substrate;

a base die attached to the substrate, the base die having a relief region with a shaped cross-section; and

a bond wire connected between an active base surface of the base die and the substrate, the bond wire extended through the shaped cross-section of the relief region.

12. The system as claimed in claim 11 wherein the bond wire includes stitch bonding connected between the active base surface of the base die and the substrate, the bond wire extended through the shaped cross-section of the relief region.

13. The system as claimed in claim 11 wherein the base die is attached to the substrate, the base die having the relief region with the shaped cross section, the relief region with the shaped cross-section is shaped as a rectangle, a triangle, or a curve.

14. The system as claimed in claim 11 further comprising:

a stacking die mounted over the base die; and

a stacking attachment layer to attach the stacking die with the base die, the stacking attachment layer covers a portion of the bond wire.

15. The system as claimed in claim 11 further comprising a stacking die mounted over the base die, the stacking die having a relief region with a shaped cross-section extended over the connection of the bond wire to the active base surface of the base die.

16. The system as claimed in claim 11 wherein:

the substrate having an active substrate surface;

the base die attached to the substrate, the base die having the relief region with the shaped cross-section around the perimeter thereof; and

the bond wire connected between the active base surface of the base die and the substrate, the bond wire ~~at least one of the bond wires~~ extended through the shaped cross-section of the relief region.

17. The system as claimed in claim 16 further comprising a stitch bond to connect the bond wire parallel to the active surface of the base die.

18. The system as claimed in claim 16 further comprising:

a stacking die mounted over the base die; and

an insulation layer attached on the stacking die, the insulation layer between the stacking die and the base die.

19. The system as claimed in claim 16 further comprising:

a stacking die mounted over the base die, the stacking die having a relief region with a shaped cross-section;

a stacking attachment layer to attach the stacking die with the base die, the stacking attachment layer covers a portion of the bond wire; and

wherein:

the bond wire connected between the active base surface of the base die and the substrate, the bond wire ~~at least one of the bond wires~~ extends through the shaped-cross section of the relief region of the stacking die.

20. The system as claimed in claim 16 further comprising a stacking die mounted over the base die, the stacking die having a relief region with a shaped cross-section extended over portions of the active base surface, the bond wire~~s~~, and portions of the substrate adjacent the bond wire~~s~~.